



Mechanical Properties and Characterization of Bonded Composites

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Deadline for manuscript
submissions:

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Message from the Guest Editor

Bonded composites are widely seen in different engineering applications at different length scales including micro-electro-mechanical systems (MEMS), fiber/matrix joints in fiber-reinforced composites, aerospace structures, and civil infrastructures. We are primarily interested in papers addressing mechanical behavior, fatigue, fracture, and damage mechanics at the interface of bonded components including adhesively bonded joints, welded components, etc. Theoretical works with experimental validations and numerical works conducted at different length scales (from atomistic to continuum) are highly encouraged. Contributions with applications in mechanical and manufacturing, aerospace, civil, biomedical, chemical, and electrical engineering are warmly welcomed. Topics of interests include (but not limited to):

- Characterization of the cracking/mechanical behavior of bonded composites
- Bonded composites under extreme environments
- Bonded composites made of advanced materials for advanced engineering applications.
- Novel fracture theories in bonded composites
- Bonded composites processed by additive manufacturing techniques.





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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal *Applied Sciences* has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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